

\*\*\* It is now 2/28/2008 3:44:16 PM \*\*\*

[File 342] Derwent Patents Citation Indx 1978-07/200809

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S1 45 S CT=US 5496775

[File 347] JAPIO Dec 1976-2007/Oct(Updated 080129)

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*\*File 347: File Histories now available for ordering when searching via DialogLink 5 and Web products, see HELP FILEHIST for more information.*

[File 350] Derwent WPIX 1963-2008/UD=200813

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*\*File 350: Chinese Utility Model registrations in English now available To order File Histories, see HELP FILEHIST for details.*

S1 66 S1:S11 FROM 347,350

[File 347] JAPIO Dec 1976-2007/Oct(Updated 080129)

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Set	Items	Description
S1	302	S (ENCAPSULA???????? OR ENVELOP????????) (4N) (WAFER???? OR DIE OR DIES OR MICROCHIP???? OR DICE OR CHIP????)
S2	66461	S (WAFER??? OR DIE OR DIES OR MICROCHIP???? OR DICE OR CHIP???? OR SUBSTRATE? ?) (3N) (SIDE? ? OR OUTER???? OR PERIPHERAL??? OR OUTSIDE? ? OR EDGE? ?)
S3	42	S S1 AND S2
S4	36	S S3 NOT PY>2002
S5	101659	S CONTACTS OR PINS OR VIAS OR BUMPS OR BALLGRIDS OR BALL {} GRIDS OR ARRAYS
S6	812	S BALLGRID OR BALL {} GRID
S7	102321	S S5:S6
S8	23	S S1 AND S7
S9	21	S S8 NOT S4
S10	20	S S9 NOT PY>2002
S11	14485	S S5 AND (WAFER? ? OR DIE OR DIES OR MICROCHIP???? OR DICE OR SUBSTRATE? ?)
S12	0	S S11 AND MILS
S13	15	S S11 AND (MICRON? ? OR UM)
S14	127	S S11 AND PLANAR????
S15	1783	S S2 AND S11
S16	13	S S14 AND S15
S17	1236191	S POLYMER? ? OR RESIN???? OR PARYLEN? OR EPOX????
S18	519	S S7 AND S17 AND S2
S19	2	S S1 AND S18
S20	131215	S SOLDER {} (COLUMN??? OR CONTACTS OR BALLS) OR CONDUCTIVE {} BUMPS OR MOUNTING {} CONNECTION? ? OR EPOXY {} BEAD? ? OR TERMINALS
S21	48836	S PINS OR VIAS OR BUMPS
S22	177579	S S6 OR S20:S21
S23	19730	S S17 AND S22

S24           865    S S2 AND S23  
S25           96    S S24 AND (DEPTH OR THICKNESS???)  
S26           81    S S25 NOT PY>2002  
S27       27230    S (COLUMN???? OR CONTACTS OR BALLS OR BUMPS OR BEADS OR  
TERMINALS OR CONTACTS) (2N) (PLURALITY OR NUMEROUS OR SET OR SETS OR  
QUANTITY OR MULTITUDE OR MYRIAD OR NUMBER OR ARRAY? ? OR COLLECTION OR  
GROUP)  
S28           6126   S (PINS OR VIAS OR BUMPS) (2N) (PLURALITY OR NUMEROUS OR  
SET OR SETS OR QUANTITY OR MULTITUDE OR MYRIAD OR NUMBER OR ARRAY? ? OR  
COLLECTION OR GROUP)  
S29       32576    S S27:S28  
S30           598    S S2 AND S29  
S31           6     S S30 AND PLANAR??????  
S32           398    S S30 NOT PY>2002  
S33           99    S S17 AND S32

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	227950	(PINS OR VIAS OR COLUMN\$3 OR CONTACTS OR BALLS OR BUMPS OR BEADS OR TERMINALS OR CONTACTS)near2(PLURALITY OR NUMEROUS OR SET OR QUANTITY OR MULTITUDE OR MYRIAD OR NUMBER OR ARRAY OR COLLECTION OR GROUP)	EPO; JPO; DERWENT	OR	ON	2008/02/28 17:25
L2	181610	(WAFER\$4 OR DIE OR DIES OR MICROCHIP OR DICE OR CHIP OR SUBSTRATE) near3 (SIDE OR OUTER\$4 OR PERIPHERAL\$4 OR OUTSIDE OR EDGE)	EPO; JPO; DERWENT	OR	ON	2008/02/28 17:26
L3	3774	1 and 2	EPO; JPO; DERWENT	OR	ON	2008/02/28 17:26
L4	2331226	encapsulat\$4 cover\$4 protect\$6	EPO; JPO; DERWENT	OR	ON	2008/02/28 17:27
L5	804	3 and 4	EPO; JPO; DERWENT	OR	ON	2008/02/28 17:27
L6	3638588	rubber polymer plastic thermoset resin rubber elastomer epoxy polyimid\$4 amid\$3 imid\$4 silicone	EPO; JPO; DERWENT	OR	ON	2008/02/28 17:28
L7	361	5 and 6	EPO; JPO; DERWENT	OR	ON	2008/02/28 17:28